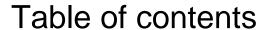


Smart home appliances – PSoC™ touch-sensing technology







IntroductionHMI Solutions





IntroductionHMI Solutions

The challenge: Making smart products is hard



Creating a delightful user experience

- > 100% of consumers want smart-home products and services that make life safer and easier
- > Small shift in customer reviews has a large impact on sales
- "One positive star on Amazon increases sales by 20%"

Improving connectivity of your products

- "60% of consumers fail to onboard smart home devices"
- On average, 40% of onboarding failures last between 8 min 60 min
- Most customers give up trying to connect their device after 2 failed attempts

While reducing costs

- "43% of organizations fail to finish a project within the original budget"
- "Number of product managers who want more resources for their projects: 100%"



Better experience and easier products

100%



Connectivity problems

60%



Fail to finish on budget

43%

Core capabilities to solve key design challenges





Intuitive Sensing Capabilities

Intuitively sensing the environment as with human-like senses for a more meaningful contextual awareness. **Ubiquitous sensors** mark the "point of beginning" of the IoT, picking up meaningful data from the environment surrounding an IoT edge device.





Providing **stable and secure connections** at lowest power consumption Wi-Fi, Bluetooth and BLE USB / USB-C.



Trusted Security

Security solutions shield connected systems and devices and protect personal privacy, intellectual property and public safety. Comprehensive security portfolio from dedicated security hardware to integrated solutions.



Flexible Processing



Microcontrollers are the **brain of IoT systems**. They control and instruct IoT devices by collecting, coordinating, processing, analyzing, and communicating data – thus making them "**smart**" at lowest power consumption.



Complete Software Ecosystem

For easy implementation of complete IoT systems: Embedded software development tools for flexible configuration, fast and easy programming of microcontrollers, implementation of cloud services, (OTA updates and data security); (Connectivity SDKs). Secure

Efficient Power Management



The power supplied is constantly managed smartly and efficiently.

Lights, temperature and movements are controlled and actuated

by intelligent power management together with power

semiconductors.



Infineon is the ideal partner for innovative Smart Home IoT Solutions







Helping customers bring high-quality, differentiated smart home products to market on time, on budget, with low risk











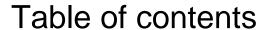
Best-in-class HMI

High Performance
Bluetooth

Secure & Reliable Wi-Fi

Low-Power Secure MCU

Innovative Sensing

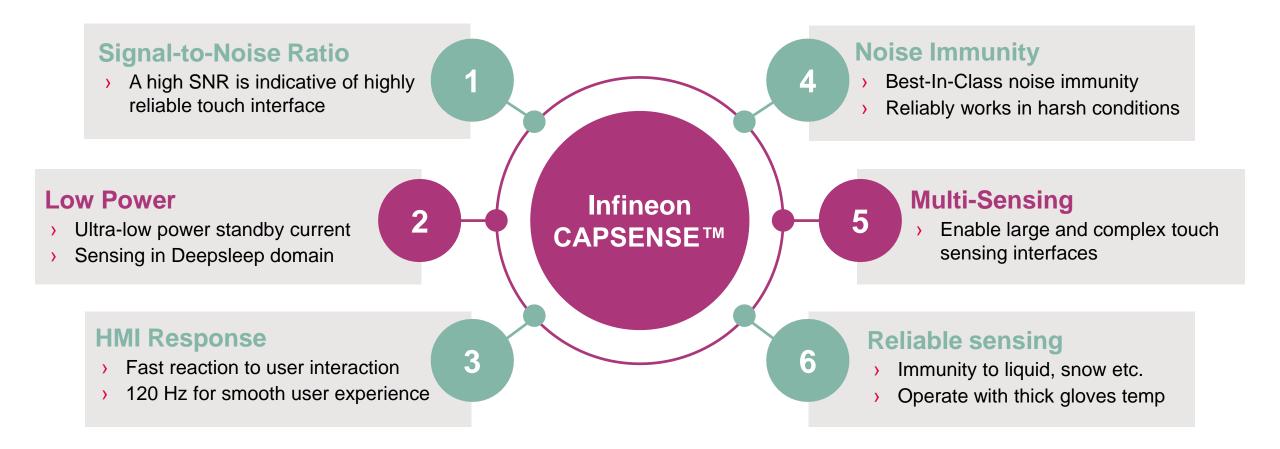




IntroductionHMI Solutions



The Infineon Solution: CAPSENSE™ Touch-Sensing Technology



Infineon Proprietary

Infineon: Trusted partner in Touch HMI Solutions



Top 1

6+ Billion

Patents

Touch HMI Solution Conventional Buttons replaced

100+ Touch Patents

Touch HMI Market Size

Touch HMI Discovery

- Touch HMI market continue to expand
- > SAM: 3 Billion by 2024
- > SOM: 1.2 Billion by 2024
- > ICW MCU PL: 140 Million chips in 2020

Copyright © Infineon Technologies AG 2023. All rights reserved.

Decades of Innovation & Leadership in Touch HMI Revolution





CapSense: Industry leading capacitive-sensing technology

- CapSense is the industry's #1 solution in sales by 4x over No.2
- Over three billion CapSense controllers have replaced more than six billion mechanical buttons
- CapSense is found everywhere, including smartphones, wearables, automotive HMI, home appliances and printers

Touch Buttons: 2003



LG Chocolate Mobile Phone

Liquid Tolerance: 2008



Whirlpool Dishwasher

Noise Immunity: 2010



HP TouchSmart Printer

Configurability: 2011



Microsoft Arc Touch Mouse

1 B Units: 2013



Samsung Galaxy Note 3



2 B Units: 2018

Fitbit Charge 3



3 B Units: 2022

Cypress's CapSense research and development begins with buttons and sliders

CapSense algorithms offer Liquid Tolerance, proximity sensing and improved noise immunity

SmartSense™ Auto-tuning revolutionizes CapSense design by removing Manual Tuning and improving noise immunity

CapSense Express™ offers configurable solutions that do not require Firmware Development

One billionth CapSense controller shipped with stylus-activated buttons

Two billionth CapSense controller shipped with Ultra Low Power CapSense

Exponentially growing under Infineon to multiple market segments

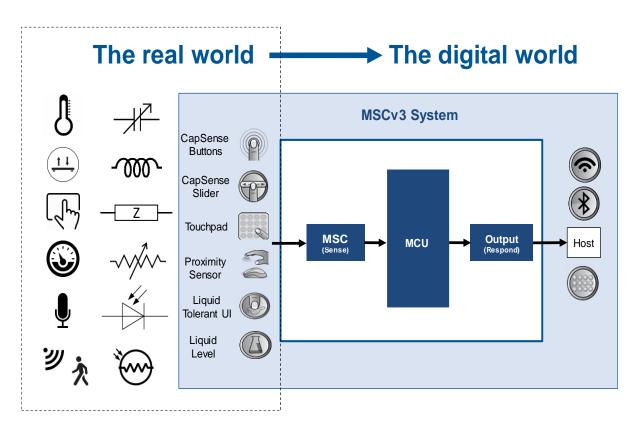
2020: Infineon introduced the next generation world leading sensing capabilities with our Multi-Sense Convertor More robust sensing intelligence and excellence at the edge



Next-Generation Sensing Technology – Multi Sense Converter

Taking world class technology today to the next level...

- An improved ratio-metric architecture (Output ~ Cs/Cref)
- Multi-Sense Converter:
 - Capacitive sensing (Self and Mutual)
 - Inductive sensing
 - Sensor (Impedance, Current & Resistor)
- > 16x higher signal-to-noise ratio performance
 - <100aF rms noise floor for Cs=8pF</p>
 - > Supports Cs up to 200pF
- > 10x lower average power consumption
 - Ultra-low power Always-ON sensing
 - Autonomous operation without CPU
- Enhanced Noise Immunity
 - Differential signal path for high DC noise rejection
 - Dithering/Chopping/CIC2/ for improved linearity/noise

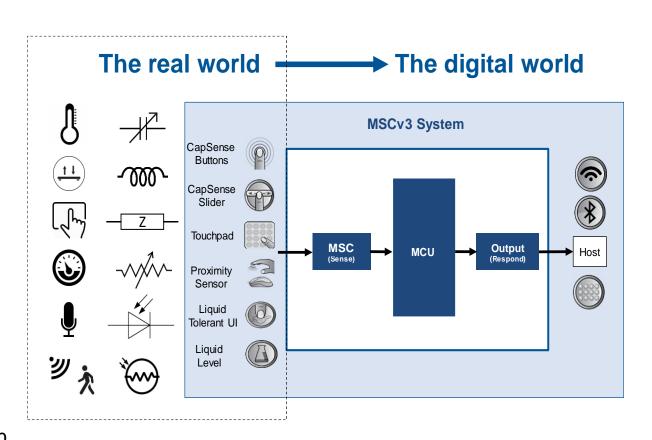




Next-Generation Sensing Technology – Multi Sense Converter

Taking World Class Technology Today to the Next Level...

- Improved ratio-metric architecture (Output ~ Cs/Cref)
- Multi-Sense Converter:
 - Capacitive sensing (Self and Mutual)
 - Inductive sensing
 - Sensor (Impedance, Current & Resistor)
- <u>16x higher</u> signal-to-noise ratio performance
 - > <100aF rms noise floor for Cs=8pF</p>
 - Supports Cs up to 200pF
- 10x lower average power consumption
 - Ultra-low power Always-ON sensing
 - Autonomous operation without CPU
- Enhanced Noise Immunity
 - Differential signal path for high DC noise rejection
 - Dithering/Chopping/CIC2/ for improved linearity/noise



Note: Requires <u>two</u> external CMOD capacitors!



Next Generation Sensing Technology - Comparison

Parameters	Competition	Infineon	Comment
Output Raw Count	Ratio — metric	$\infty rac{C_S}{C_{ref}}$	
Input dynamic range	+/- 8pF	200pF	
Converter resolution (ENOB)	10-bits	13.5 bits	CDC with 256 decimation (3ms scan time) vs MSC no decimation.
Driven Shield	Yes	Yes – Active & Passive	Passive shield Csh < 100pF, lower power
Sensing Methods	Self-cap, Mutual-cap	Self-cap, Mutual-Cap, Inductive, Multi-Sense	Multi-Sense is flexible AFE.
Noise Immunity	Spread Spectrum Clock, Freq. Hopping	Spread Spectrum Clock, Chopping, CIC2 filter, CDAC dither, Multi-Phase	
Autonomous scan	No	Yes	Infineon: Scan without CPU, up to 32 sensors
Multi-Chip / Multi-Channel	No	Yes	
Always-On Sensing	No	Yes (16 sensors)	Sensing in Deepsleep with hardware signal detection for wakeup
Average Active current	3 - 4.7 mA @ 128 Hz	170 uA @ 128 Hz	With 13 sensors
Average look-for-touch current	11 - 300 uA @ 10 -128 Hz	4.6 uA @ 16 Hz	

Infineon's CapSense technology delivers the best performance and lowest system power consumption in the market!

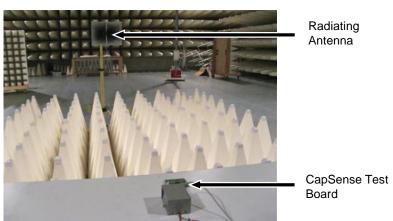




Thickness Overlay	Parasitic Capacitance	CapSense SNR (IEC Spec = 5:1)
1.0 mm (Reference)	10 pF	>150:1
2.0 mm	10 pF	>73:1
5.0 mm	10 pF	>37:1
6.0 mm	10 pF	>25:1

IEC Standard	Description	IEC Standard Requirement	CapSense
61000-4-3/6-1	Radiated immunity (80 MHz to 2.4 GHz)	SNR > 5:1, No false trigger, > 10 V/m	10:1 SNR, No false triggers
61000-6-3	Radiated emission	30.0 dBμV/m, 30-230 MHz 37.5 dBμV/m, 230-1,000 MHz	< 25 dBµV/m < 37 dBµV/m

Radiated Immunity Test Room for CapSense EMI Testing



Radiated Emission Test Data 70 (E) 40 40 30 IEC 61000-6-3 Limit Actual CapSense Data 0 30 100 200 1,000 Frequency (MHz)

CapSense buttons "just work" because of rigorous engineering and testing

Liquid level sensing



- Liquid level sensing
- Different sensing methods available
- Several use cases analyzed with customers
- > Status: In mass production (e.g. AdBlue tanks)

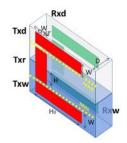
Coffee machine



Ink printer cartridge

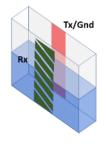


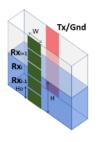
1. Ratiometric



2. Differential

3. Centroid based







CY8CKIT-022

- > Incl. 2 sensors and a water bottle.
- To be combined with PSoC 4 or PSoC 6 Kit with Arduino header





Button Proximity Rotary Encoder Linear Encoder Flow Hybrid Inductive & Capacitive

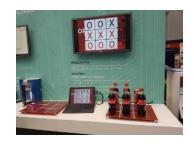


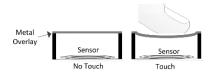


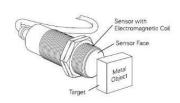


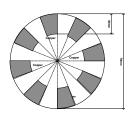


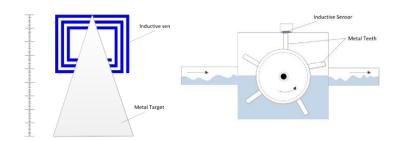
















Use case comparison

Good

Poor

Category	Use cases	Capacitive			Inductive	
3 ,		Self	Self + Shield	Mutual		
	# Buttons	# of I/O	# of I/O	(# TX I/O)*(#RX I/O)	0.5* (# of I/O)	
Finger Touch	Touch Duttons	Yes	Yes	Yes	No	
ū	Touch Buttons	Cp < 200 pF	Cp < 200 pF	Cp < 1000 pF	Cp not an issue	
	Proximity	Ok	Yes – best performance	No	No	
	Proximity Gestures	Yes		No	No	
	Sliders	Yes	Yes	Yes	No	
	Touchpad	Yes	Yes	Yes	No	
	Touchpad Gestures	Two fingers	Two fingers	Multi-Touch	No	
Liquid level sensing	Liquid level sensing	Ok performance	Ok performance	Yes – best performance	Ok with metal float	
Force Sensing	Force Sensing	Ok performance	Yes	Yes	Yes	
Rotary encoder	Rotary encoder	No	No	No	Yes	
	Metal over Touch Buttons	Ok with Gnd metal	Ok with Gnd metal	No	Yes – best performance, No metal Gnd needed	
Metal Touch	Sliders	Ok with Gnd metal	Ok with Gnd metal	No	Yes – best performance, No metal Gnd needed	
	Metal Proximity	Ok with Gnd metal	Ok with Gnd metal	No	Yes – best performance, No metal Gnd needed	
Waterproof	Waterproof Buttons	No	Yes	Yes	Yes	
	Waterproof Sliders	No	Yes	No	Yes	
# Capacitors	# Capacitors	1 (CMOD)	2 (CMOD + CSH)	2 (CMOD + CSH_TANK)	2+ #SENSORS (CMOD + CSH_TANK+ #SENSORS)	
Typical Applications	Typical Applications	Mech. Button replacement Non metal proximity sensing Low-Cost Touchpad	Proximity sensing Liquid Tolderance	Multi-Touch Touchpad Touch screen Liquid level detection	Metal Buttons Rotary sensing Linear Encoding Force Sensing	

Consumer/IoT: PSoC™ 6 – Ultra-Low-Power | Flexibility | Hardware-based security and root of trust



PSoC™ 61 Line

Entry Level MCUs
(Single Core Apps CPU - Arm® Cortex®-M4)

CY8C614A, CY8C6148
Flash / SRAM (614A) – 2048 KB / 1024 KB
Flash / SRAM (6148) – 1024 KB / 512 KB

<u>Key Peripherals</u> – **SD Host x 2**, SCB x 13, **PDM-PCM, I2S**, TCPWM x 32, 102 IOs

Packages – 128-TQFP, 124-BGA, 102-WLCSP, 68-QFN

CY8C61x7, CY8C61x6

<u>Flash / SRAM (6147)</u> – 1024 KB / 288 KB <u>Flash / SRAM (6146)</u> – 512 KB / 128 KB

<u>Key Peripherals</u> – SCB x 9, **PDM-PCM**, **I2S**, **12-bit VDAC**, **Opamps x2**, TCPWM x 32, 100 IOs

Packages -124-BGA, 80-WLCSP

CY8C6145

Flash / SRAM- 512 KB / 256 KB

<u>Key Peripherals</u> – **SD Host, CAN-FD**, SCB x 6. TCPWM x 12. 64 IOs

Packages -100-TQFP, 68-QFN, 49-WLCSP

CY8C6144

Flash / SRAM - 256 KB / 128 KB

<u>Key Peripherals</u> – **CAN-FD, 12-bit VDAC, 12-bit ADC x2, Opamps x2,** SCB x 6, TCPWM x 12, 62 IOs

Packages -80-TQFP, 68-QFN, 64-TQFP

PSoC™ 62 Line

High Performance MCUs (Dual Core Apps CPU - Arm® Cortex®-M4, Arm® Cortex®-M0+)

CY8C624A, CY8C6248

<u>Flash / SRAM (624A)</u> – 2048 KB / 1024 KB Flash / SRAM (6248) – 1024 KB / 512 KB

<u>Key Peripherals</u> – SD Host x 2, SCB x 13, PDM-PCM, I2S, TCPWM x 32, 102 IOs

Packages – 128-TQFP, 124-BGA, 102-WLCSP, 68-QFN

CY8C6247, CY8C6246

<u>Flash / SRAM (6247)</u> – 1024 KB / 288 KB <u>Flash / SRAM (6246)</u> – 512 KB / 128 KB

<u>Key Peripherals</u> – SCB x 9, **PDM-PCM**, **I2S**, **12-bit VDAC**, **Opamps x2**, TCPWM x 32, 100 IOs

Packages -124-BGA, 80-WLCSP

CY8C6245

Flash / SRAM- 512 KB / 256 KB

<u>Key Peripherals</u> – SD Host, CAN-FD, SCB x 6. TCPWM x 12. 64 IOs

Packages -100-TQFP, 68-QFN,49-WLCSP

CY8C6244

Flash / SRAM- 256 KB / 128 KB

Key Peripherals – CAN-FD, 12-bit VDAC, 12-bit ADC x2, Opamps x2, SCB x 6, TCPWM x 12. 62 IOs

Packages -80-TQFP, 68-QFN, 64-TQFP

PSoC™ 63 Line

Bluetooth® Low Energy MCUs (Dual Core Apps CPU - Arm® Cortex®-M4, Arm® Cortex®-M0+)

CY8C6347, CY8C6346

Flash / SRAM (6347) - 1024 KB / 288 KB

PDM-PCM, I2S, 12-bit VDAC, Opamps x2,

104-M-CSP, 68-QFN

Flash / SRAM (6346) - 512 KB / 128 KB

Key Peripherals - BLE v5.0, SCB x 9,

Packages -124-BGA, 116-BGA,

TCPWM x 32, 84 IOs

PSoC™ 64 Line

Secured MCUs

(Arm® Cortex®-M0+ - Secure CPU, Arm® Cortex®-M4 - Apps CPU)

CYB0644A

Flash / SRAM (62xA) - 1856 KB / 944 KB

Key Peripherals – SD Host x 2, SCB x 13, PDM-PCM, I2S, TCPWM x 32, 102 IOs

Packages - 124-BGA, 102-WLCSP

CYB06447

Flash / SRAM (6347) - 832 KB / 176 KB

Key Peripherals – BLE v5.0, SCB x 9, PDM-PCM, I2S, 12-bit VDAC, Opamps x2, TCPWM x 32. 84 IOs

Packages –124-BGA (with BLE, w/o BLE), 116-BGA (BLE only)

CYB06445

Flash / SRAM - 384 KB / 176 KB

<u>Key Peripherals</u> – SD Host, CAN-FD, SCB x 6, TCPWM x 12, 64 IOs

Packages -68-QFN

Common features (All PSoC™ 6 MCUs)

- Arm® Cortex®-M4 CPU
- + Arm[®] Cortex[®]-M0+ CPU (except PSoC[™] 61)
- Capacitive Touch Sensing
- Crypto Accelerator
- ROM based Root of Trust
- DMA Controllers
- QSPI External Flash
- Serial Comm (SCB) I2C / SPI / UART
- Timers, Counters, PWMs (TCPWM)
- USB Full Speed (Device / Host)
- 12-bit SAR ADC x1
- Low Power Comparators x2
- Segment LCD Drive

Smart I/Os

Consumer/IoT: PSoC™ 4

Flexibility | CapSense® | Ease-of-Use



	PSoC MCU PSoC 4000	Intelligent Analog PSoC 4100		Programmable Digital PSoC 4200	Analog Coprocessor PSoC 4A00	Application Specific PSoC 4500 , 4700
			BL = BLE-Series	S = S-Series M = M-Series	L = L-Series	
		CY8C4129-S 24-MHz M0+, 384K/32K ¹ CMP ² , Opamp, ADC ³ SCB ⁴ , MSC ¹² , Smart I/O ⁶	CY8C4149-S 48-MHz M0+, 384K/32K CMP, Opamp, ADC SCB, MSC, Smart I/O			
Performance and Integration CAB-WH-SP WSC1: CAB-WH-SP CAB		CY8C4128-S 24-MHz M0+, 256K/32K ¹ CMP ² , Opamp, ADC ³ SCB ⁴ , IDAC ⁵ , Smart I/O ⁶	CY8C4148-S 48-MHz M0+, 256K/32K CMP, Opamp, ADC SCB, IDAC, Smart I/O			
		CY8C4147-S 48-MHz M0+,128K/16K CMP, Opamp, ADC SCB, IDAC, Smart I/O	CY8C4128-BL 24-MHz M0, 256K/32K CMP, Opamp, ADC, SCB IDAC, BLE ⁷	CY8C4247-M 48-MHz M0, 128K/16K, CMP, Opamp, ADC, SCB IDAC, UDB ⁸ , CAN ⁹		CY8C45xx-S Motor Control
		CY8C4127-S 24-MHz M0+, 128K/16K CMP, Opamp, ADC SCB, IDAC, Smart I/O	CY8C4127-BL 24-MHz M0, 128K/16K CMP, Opamp, ADC, SCB IDAC, BLE	CY8C4246-M 48-MHz M0, 64K/8K, CMP, Opamp, ADC, SCB IDAC, UDB CY8C4248-BL 48-MHz M0, 256K/32K CMP, Opamp, ADC, SCB IDAC, BLE, UDB		48-MHz M0+, 256K/32K MCA ¹¹ , CMP, Opamp 2X ADC, SCB, IDAC Smart I/O, ECO
погта	CY8C40x-T 48-MHz M0+, 64 K/8 K CMP, ADC, SCB, MSC12, Smart I/O	CY8C4127-M 24-MHz M0, 128K/16K CMP, Opamp, ADC, SCB IDAC	CY8C4146-S 48-MHz M0+, 64K/8K CMP, Opamp, ADC, SCB IDAC, Smart I/O	CY8C4246-DS 48-MHz M0, 64K/8K CMP, SCB UDB, Smart I/O CY8C4247-BL 48-MHz M0, 128K/16K CMP, Opamp, ADC, SCE IDAC, BLE, UDB	3	CY8C47xx-S
- Pe	CY8C4045-S 48-MHz M0+, 32K/4K CMP, ADC, SCB IDAC, Smart I/O	CY8C4126-M 24-MHz M0, 64K/8K CMP, Opamp, ADC, SCB IDAC	CY8C41xx-PS 48-MHz M0+, 32K/4K CMP, Opamp, ADC SCB, VDAC, Smart I/O	CY8C4245-DS 48-MHz M0, 32K/4K CMP, SCB UDB, Smart I/O CY8C4248-L 48-MHz M0, 256K/32K CMP, Opamp, ADC, SCE IDAC, UDB, CAN, USB		Inductive Sensing 48-MHz M0+, 32K/4K CMP, Opamp, UAB ¹⁰ ADC, SCB, VDAC Smart I/O
	CY8C4024-S 24-MHz M0+, 16K/2K CMP, ADC, SCB IDAC, Smart I/O	CY8C4125 24-MHz M0, 32K/4K CMP, Opamp, ADC, SCB IDAC	CY8C4125-S 24-MHz M0+, 32K/4K CMP, Opamp, ADC, SCB IDAC, Smart I/O	CY8C4245 48-MHz M0, 32K/4K CMP, Opamp, ADC, SCB IDAC, UDB CY8C4247-L 48-MHz M0, 128K/16K CMP, Opamp, ADC, SCB IDAC, UDB, CAN, USB	3	
	CY8C4014 16-MHz M0, 16K/2K CMP, I ² C, IDAC	CY8C4124 24-MHz M0, 16K/4K CMP, Opamp, ADC, SCB IDAC	CY8C4124-S 24-MHz M0+, 16K/4K CMP, Opamp, ADC, SCB IDAC, Smart I/O	CY8C4244 48-MHz M0, 16K/4K, CMP, Opamp, ADC, SCB IDAC, UDB CY8C4246-L 48-MHz M0, 64K/8K CMP, Opamp, ADC, SCE IDAC, UDB, CAN, USB		
mparat	tor ⁵ Current-out	munication block tput DAC I programmable digital logic in	⁸ Universal	Low Energy 10 Universal analog block Statu digital block 11 Motor Control Accelerator area network 12 Multi-sense convertor Availab	us 🔲 🔲	Production

PSoC™ 62X4 Family



Applications

Motor and power control, LPWAN and other Consumer

Features

- MCU Subsystem
- Dual-core architecture: 150-MHz Arm® Cortex®-M4 and 100-MHz Arm Cortex-M0+
- Ultra-low-power (0.9 V) and low-power (1.1 V) operation mode
- Up to 256K Flash, 128KB SRAM with DMA
- Analog Blocks
- 2 x opamps, 2 x low-power comparators (CMP)
- 2x 12-bit SAR ADC (2 Msps) and 12-bit DAC, operable under deep-sleep mode
- > CapSense® capacitive-sensing block
- Digital Blocks and Communication Interfaces
 - 8 x 16-bit and 4 x 32-bit timer/counter/pulse-width modulation blocks (TCPWM)¹
 - 5 x serial communication blocks (SCBs)², 1x deep-sleep SCB
- USB 2.0 (Host and Device)
- SMIF (Serial memory interface for execute-in-place, encrypted Quad-SPI)
- Security Features
- Advanced cryptographic coprocessor (Crypto) and True random number generator
- One-time programmable eFUSE⁶ for secure key storage
- Secure over-the-air (OTA) firmware update with read-while-write Flash technology for firmware updates
- > I/O Subsystem: Up to 62 GPIOs
- Packages: 80-TQFP, 68-QFN, 64-TQFP

Collateral

Datasheet: Preliminary

PSoC™ 62x4 Family MCU Subsystem **Analog Blocks** I/O Subsystem **CMP Opamp** GPIO x8 **x2** GPIO x8 1x 12-bit 12-bit SAR with SP FPU7 DAC ADC x2 150-MHz GPIO x8 CapSense I-Cache 8KB GPIO x8 **Digital Blocks** GPIO x8 **TCPWM** Cortex -M0+ GPIO x8 100-MHz Communication Interfaces I-Cache 8KB GPIO x8 SCB² x6 SRAM GPIO x8 128KB Flash CAN-FD x1 GPIO x8 256KB Crypto GPIO x8 SMIF⁵ DMA (Quad-SPI) GPIO x12 **eFUSE USB 2.0** GPIO x12 RTC

Availability

Sampling: Now Production: Q321

⁷ Single-Precision Floating-Point Unit

20

¹ Configurable as an 8-bit, 16-bit timer, or 32-bit counter or PWM
⁵ Controller Area Network

² Configurable as a UART, SPI, or I²C interface ⁶ One-time programmable bits for secure key storage

PSoC™ 4x00T Series



Applications

Touch controller for Wearable, Hearable, Smart devices and other consumer applications

Features

- 32-bit MCU Subsystem
- 48-MHz Arm® Cortex®-M0+ CPU
- 64KB flash and 8KB SRAM
- Programmable Analog Blocks
 - 5th-Generation CAPSENSE block (Multi Sense Converter MSC_LP)
- Ultra-low power Always-ON sensing CapSense and Inductive sensing
- > Programmable Digital Blocks
 - Two 16-bit timer/counter/pulse-width modulator (TCPWM) blocks
 - Two serial communication blocks (SCBs) that are configurable as I²C, SPI, or UART
- > I/O Subsystem
 - Up to 20 GPIOs, including 16 sensors
- > Packages
 - 25-WLCSP, 24-QFN, 16-QFN

MCU Subsystem **Programmable Analog** I/O Subsystem Blocks GPIO x8 arm GPIO x8 MSC LP GPIO x4 48 MHz Flash 64KB SRAM 8KB **Serial Wire Debug Programmable Digital Blocks** TCPWM x2 SCB x2

Collateral

Datasheet: Contact Sales

Availability

Sampling: Q4'2022 Production: Q1'2023

PSoC™ 4x00T Series



Part of your life. Part of tomorrow.